SWITCHMODE Schottky Power Rectifier

Surface Mount Power Package

This series of Power Rectifiers employs the Schottky Barrier principle in a large metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use in low voltage, high frequency switching power supplies, free wheeling diodes, and polarity protection diodes.

Features

- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured Not Sheared!
- AEC-Q101 Qualified and PPAP Capable
- NBRB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb-Free*

Mechanical Characteristics:

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings:
 - Machine Model = C (> 400 V)
 - ◆ Human Body Model = 3B (> 8000 V)



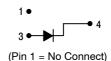
ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 8 AMPERES, 100 VOLTS



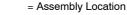
D²PAK CASE 418B



MARKING DIAGRAM



B8H100 = Specific Device Code



= Year

A

G

WW = Work Week

- = Pb-Free Package
- AKA = Polarity Indicator

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|---------------------------------|-----------------------|
| MBRB8H100T4G | D ² PAK (Pb–Free) | 800 / Tape & Reel |
| NBRB8H100T4G | D ² PAK (Pb–Free) | 800 / Tape & Reel |

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|--|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 100 | V |
| Average Rectified Forward Current (Rated V _R) T _C = 171°C | I _{F(AV)} | 8 | A |
| Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz) T _C = 171°C | I _{FRM} | 16 | A |
| Max Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz, 25°C) | I _{FSM} | 250 | A |
| Operating Junction and Storage Temperature Range (Note 1) | T _J , T _{stg} | -65 to +175 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|---|-----------|------|
| Thermal Resistance Junction-to-Case (Note 2) Junction-to-Ambient | ${\sf R}_{	heta { m JC}} \ {\sf R}_{	heta { m JA}}$ | 1.1 44 | °C/W |

2. When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS

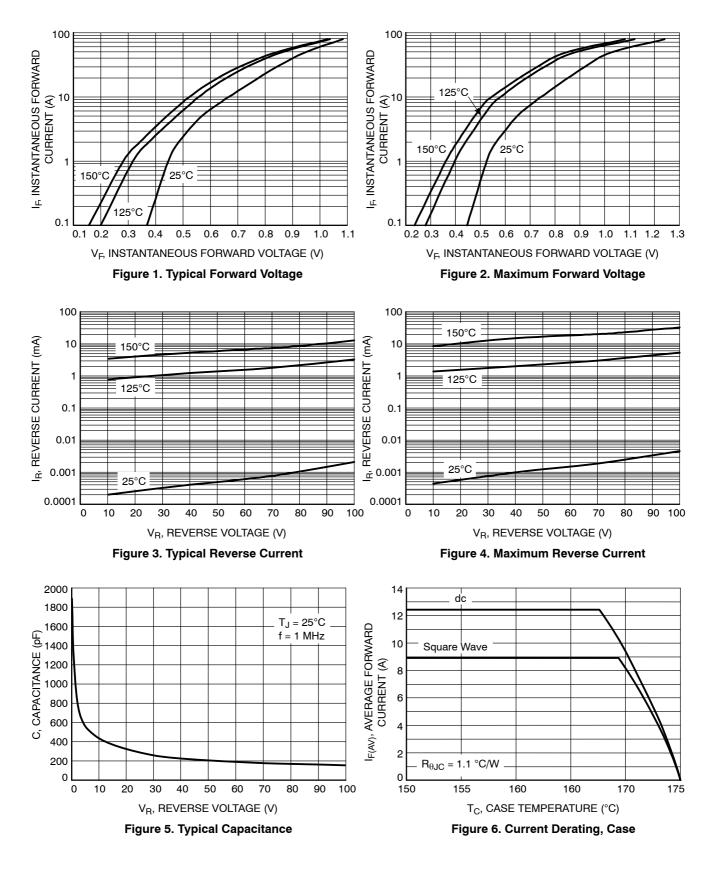
| Characteristic | Symbol | Value | Unit |
|---|----------------|--------------|----------|
| Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 8 A, T_J = 25^{\circ}C$) ($I_F = 8 A, T_J = 125^{\circ}C$) | VF | 0.71 0.55 | V |
| Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$) | I _R | 4.5 5.3 | μA mA |

DYNAMIC CHARACTERISTICS (Per Leg)

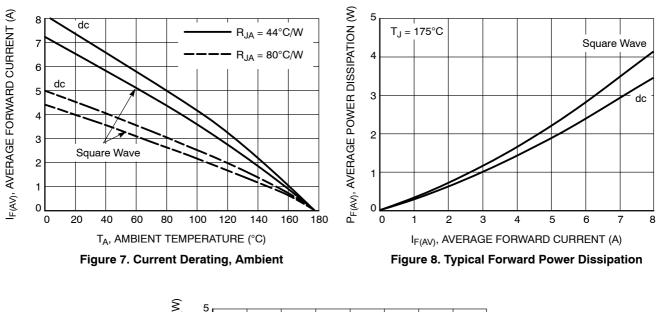
| Capacitance | CT | | pF |
|--|----|-----|----|
| $(V_R = 4.0 \text{ V}, T_C = 25^{\circ}\text{C}, \text{ Frequency} = 1.0 \text{ MHz})$ | | 600 | |

3. Pulse Test: Pulse Width = 300 $\mu s,$ Duty Cycle < 2.0%

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



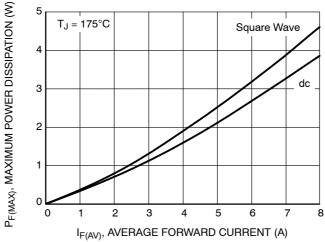
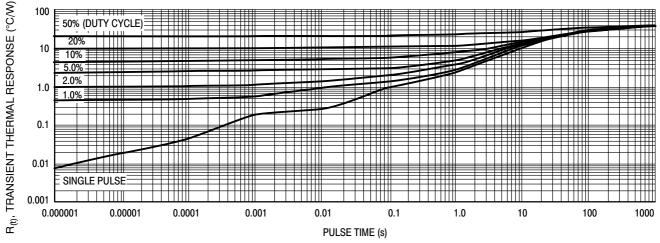


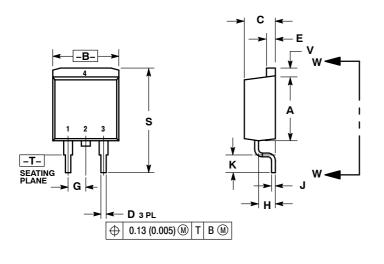
Figure 9. Maximum Forward Power Dissipation





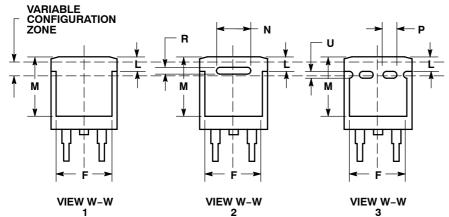
PACKAGE DIMENSIONS

D²PAK 3 CASE 418B-04 ISSUE K

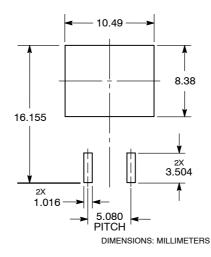


NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

| | INCHES | | MILLIN | IETERS |
|-----|-----------|-------|----------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.340 | 0.380 | 8.64 | 9.65 |
| В | 0.380 | 0.405 | 9.65 | 10.29 |
| С | 0.160 | 0.190 | 4.06 | 4.83 |
| D | 0.020 | 0.035 | 0.51 | 0.89 |
| Е | 0.045 | 0.055 | 1.14 | 1.40 |
| F | 0.310 | 0.350 | 7.87 | 8.89 |
| G | 0.100 BSC | | 2.54 BSC | |
| н | 0.080 | 0.110 | 2.03 | 2.79 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| К | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.052 | 0.072 | 1.32 | 1.83 |
| Μ | 0.280 | 0.320 | 7.11 | 8.13 |
| Ν | 0.197 REF | | 5.00 REF | |
| Р | 0.079 REF | | 2.00 REF | |
| R | 0.039 REF | | 0.99 REF | |
| S | 0.575 | 0.625 | 14.60 | 15.88 |
| V | 0.045 | 0.055 | 1.14 | 1.40 |



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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